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CYBLE-214009-00

EZ-BLE™ PSoC® Module

General Description

The Cypress CYBLE-214009-00 is a fully certified and qualified module supporting Bluetooth® Low Energy (BLE) wireless communication. The CYBLE-214009-00 is a turnkey solution and includes onboard crystal oscillators, trace antenna, passive components, and the Cypress PSoC® 4 BLE. Refer to the PSoC® 4 BLE datasheet for additional details on the capabilities of the PSoC 4 BLE device used on this module.

The EZ-BLE™ PSoC® module is a scalable and reconfigurable platform architecture. It combines programmable and reconfigurable analog and digital blocks with flexible automatic routing. The CYBLE-214009-00 also includes digital programmable logic, high-performance analog-to-digital conversion (ADC), opamps with comparator mode, and standard communication and timing peripherals.

The CYBLE-214009-00 includes a royalty-free BLE stack compatible with Bluetooth 4.1 and provides up to 25 GPIOs in a small 11 × 11 × 1.80 mm package. The CYBLE-214009-00 is drop-in compatible with the CYBLE-014008-00 EZ-BLE Module.

The CYBLE-214009-00 is a complete solution and an ideal fit for applications seeking a highly integrated BLE wireless solution.

Module Description

- Module size: 11.0 mm × 11.0 mm × 1.80 mm (with shield)
- Drop-in compatible with CYBLE-014008-00
- 256-KB flash memory, 32-KB SRAM memory
- Up to 25 GPIOs configurable as open drain high/low, pull-up/pull-down, HI-Z analog, HI-Z digital, or strong output
- Bluetooth 4.1 qualified single-mode module
  - QDID: 79480
  - Declaration ID: D029646
- Certified to FCC, CE, MIC, KC, and IC regulations
- Industrial temperature range: –40 °C to +85 °C
- 32-bit processor (0.9 DMIPS/MHz) with single-cycle 32-bit multiply, operating at up to 48 MHz
- Watchdog timer with dedicated internal low-speed oscillator (ILO)
- Two-pin SWD for programming

Power Consumption

- TX output power: –18 dbm to +3 dbm
- Received signal strength indicator (RSSI) with 1-dB resolution
- TX current consumption of 15.6 mA (radio only, 0 dbm)
- RX current consumption of 16.4 mA (radio only)
- Low power mode support
  - Deep Sleep: 1.3 µA with watch crystal oscillator (WCO) on
  - Hibernate: 150 nA with SRAM retention
  - Stop: 60 nA with XRES wakeup

Programmable Analog

- Four opamps with reconfigurable high-drive external and high-bandwidth internal drive, comparator modes, and ADC input buffering capability; can operate in Deep-Sleep mode
- 12-bit, 1-Msps SAR ADC with differential and single-ended modes; channel sequencer with signal averaging
- Two current DACs (IDACs) for general-purpose or capacitive sensing applications on any pin
- One low-power comparator that operate in Deep-Sleep mode

Programmable Digital

- Four programmable logic blocks called universal digital blocks, (UDBs), each with eight macrocells and datapath
- Cypress-provided peripheral Component library, user-defined state machines, and Verilog input

Capacitive Sensing

- Cypress CapSense Sigma-Delta (CSD) provides best-in-class SNR (> 5:1) and liquid tolerance
- Cypress-supplied software component makes capacitive-sensing design easy
- Automatic hardware-tuning algorithm (SmartSense™)

Segment LCD Drive

- LCD drive supported on all GPIOs (common or segment)
- Operates in Deep-Sleep mode with four bits per pin memory

Serial Communication

- Two independent runtime reconfigurable serial communication blocks (SCBs) with I^2C, SPI, or UART functionality

Timing and Pulse-Width Modulation

- Four 16-bit timer, counter, pulse-width modulator (TCPWM) blocks
- Center-aligned, Edge, and Pseudo-random modes
- Comparator-based triggering of Kill signals for motor drive and other high-reliability digital logic applications

Up to 25 Programmable GPIOs

- Any GPIO pin can be CapSense, LCD, analog, or digital

More Information

Cypress provides a wealth of data at www.cypress.com to help you to select the right module for your design, and to help you to quickly and effectively integrate the module into your design.

- Overview: EZ-BLE Module Portfolio, Module Roadmap
- EZ-BLE PSoC Product Overview
- PSoC 4 BLE Silicon Datasheet
- Application notes: Cypress offers a number of BLE application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with EZ-BLE modules are:
  - AN96841 - Getting Started with EZ-BLE Module
  - AN94020 - Getting Started with PSoC® 4 BLE
  - AN97060 - PSoC® 4 BLE and PRoC™ BLE - Over-The-Air (OTA) Device Firmware Upgrade (DFU) Guide
  - AN91162 - Creating a BLE Custom Profile
  - AN91184 - PSoC 4 BLE - Designing BLE Applications
  - AN92584 - Designing for Low Power and Estimating Battery Life for BLE Applications
  - AN85951 - PSoC® 4 CapSense® Design Guide
  - AN95089 - PSoC® 4/PRoC™ BLE Crystal Oscillator Selection and Tuning Techniques
  - AN91445 - Antenna Design and RF Layout Guidelines
- Technical Reference Manual (TRM):
  - PSoC® 4 BLE Technical Reference Manual
  - PSOC(R) 4 BLE Registers Technical Reference Manual
- Knowledge Base Articles
  - KBA10894 - Pin Mapping Differences Between the EZ-BLE™ PSoC™ Evaluation Board (CYBLE-214009-EVAL) and the BLE Pioneer Kit (CY8CKIT-042-BLE) - KBA10894
  - KBA210574 - RF Regulatory Certifications for CY-BLE-014008-00 and CYBLE-214009-00 EZ-BLE™ PSoC® Modules - KBA210574
  - KBA97095 - EZ-BLE™ Module Placement
  - KBA213976 - FAQ for BLE and Regulatory Certifications with EZ-BLE modules
  - KBA210802 - Queries on BLE Qualification and Declaration Processes
- Development Kits:
  - CYBLE-214009-EVAL, CYBLE-214009-00 Evaluation Board
  - CY8CKIT-042-BLE, Bluetooth® Low Energy (BLE) Pioneer Kit
  - CY8CKIT-002, PSoC® MiniProg3 Program and Debug Kit
- Test and Debug Tools:
  - CYSmart, Bluetooth® LE Test and Debug Tool (Windows)
  - CYSmart Mobile, Bluetooth® LE Test and Debug Tool (Android/iOS Mobile App)

Two Design Environments to Get You Started Quickly

PSoC® Creator™ Integrated Design Environment (IDE)

PSoC Creator is an Integrated Design Environment (IDE) that enables concurrent hardware and firmware editing, compiling and debugging of PSoC 3, PSoC 4, PSoC 5LP, PSoC 4 BLE, PRoC BLE, and EZ-BLE module systems with no code size limitations. PSoC peripherals are designed using schematic capture and simple graphical user interface (GUI) with over 120 pre-verified, production-ready PSoC Components™.

PSoC Components are analog and digital “virtual chips,” represented by an icon that users can drag-and-drop into a design and configure to suit a broad array of application requirements.

Bluetooth Low Energy Component

The Bluetooth Low Energy Component inside PSoC Creator provides a comprehensive GUI-based configuration window that lets you quickly design BLE applications. The Component incorporates a Bluetooth Core Specification v4.1 compliant BLE protocol stack and provides API functions to enable user applications to interface with the underlying Bluetooth Low Energy Sub-System (BLESS) hardware via the stack.

EZ-Serial™ BLE Firmware Platform

The EZ-Serial Firmware Platform provides a simple way to access the most common hardware and communication features needed in BLE applications. EZ-Serial implements an intuitive API protocol over the UART interface and exposes various status and control signals through the module’s GPIOs, making it easy to add BLE functionality quickly to existing designs.

Use a simple serial terminal and evaluation kit to begin development without requiring an IDE. Refer to the EZ-Serial webpage for user manuals and instructions for getting started as well as detailed reference materials.

EZ-BLE modules are pre-flashed with the EZ-Serial Firmware Platform. If you do not have EZ-Serial pre-loaded on your module, you can download each EZ-BLE module’s firmware images on the EZ-Serial webpage.

Technical Support

- Frequently Asked Questions (FAQs): Learn more about our BLE ECO System.
- Forum: See if your question is already answered by fellow developers on the PSoC 4 BLE and PRoC BLE forums.
- Visit our support page and create a technical support case or contact a local sales representatives. If you are in the United States, you can talk to our technical support team by calling our toll-free number: +1-800-541-4736. Select option 2 at the prompt.

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Overview

Module Description

The CYBLE-214009-00 module is a complete module designed to be soldered to the main host board.

Module Dimensions and Drawing

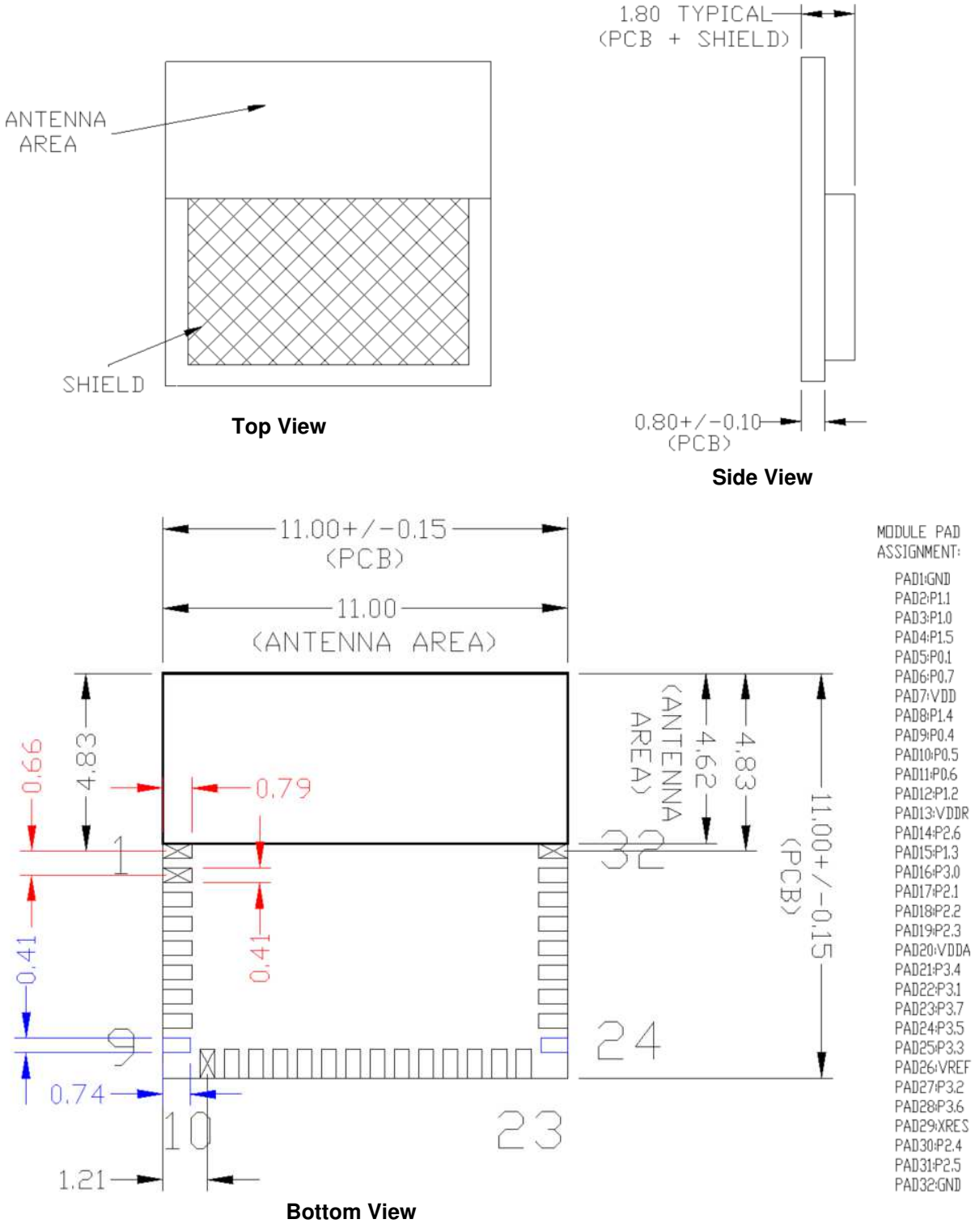
Cypress reserves the right to select components (including the appropriate BLE device) from various vendors to achieve the BLE module functionality. Such selections will guarantee that all height restrictions of the component area are maintained. Designs should be completed with the physical dimensions shown in the mechanical drawings in Figure 1 on page 5. All dimensions are in millimeters (mm).

Table 1. Module Design Dimensions

Dimension Item		Specification
Module dimensions	Length (X)	11.00 ± 0.15 mm
	Width (Y)	11.00 ± 0.15 mm
Antenna location dimensions	Length (X)	11.00 ± 0.15 mm
	Width (Y)	4.62 ± 0.15 mm
PCB thickness	Height (H)	0.80 ± 0.10 mm
Shield height	Height (H)	1.00 ± 0.10 mm
Maximum component height	Height (H)	1.00 mm typical (shield)
Total module thickness (bottom of module to highest component)	Height (H)	1.80 mm typical

See Figure 1 on page 5 for the mechanical reference drawing for CYBLE-214009-00.

Figure 1. Module Mechanical Drawing



Top View

Side View

Bottom View

Note
1. No metal should be located beneath or above the antenna area. Only bare PCB material should be located beneath the antenna area. For more information on recommended host PCB layout, see Figure 3 on page 6, Figure 4 and Figure 5 on page 7, and Figure 6 and Table 3 on page 8.

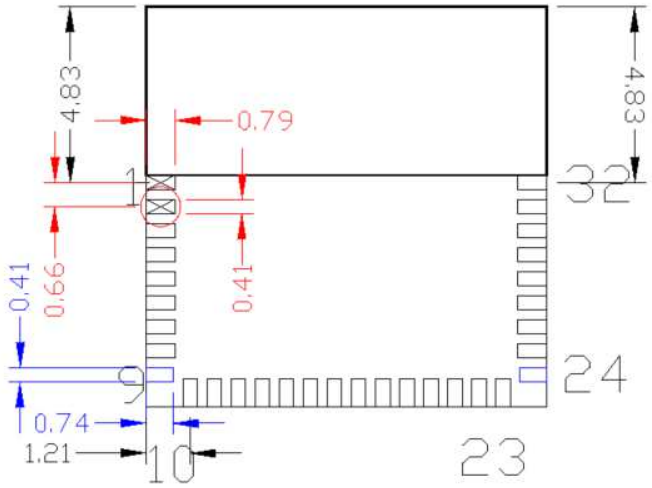
Pad Connection Interface

As shown in the bottom view of Figure 1 on page 5, the CYBLE-214009-00 connects to the host board via solder pads on the back of the module. Table 2 and Figure 2 detail the solder pad length, width, and pitch dimensions of the CYBLE-214009-00 module.

Table 2. Solder Pad Connection Description

Name	Connections	Connection Type	Pad Length Dimension	Pad Width Dimension	Pad Pitch
SP	32	Solder Pads	Pad9/Pad24: 0.74 mm All Others: 0.79 mm	0.41 mm	0.66 mm

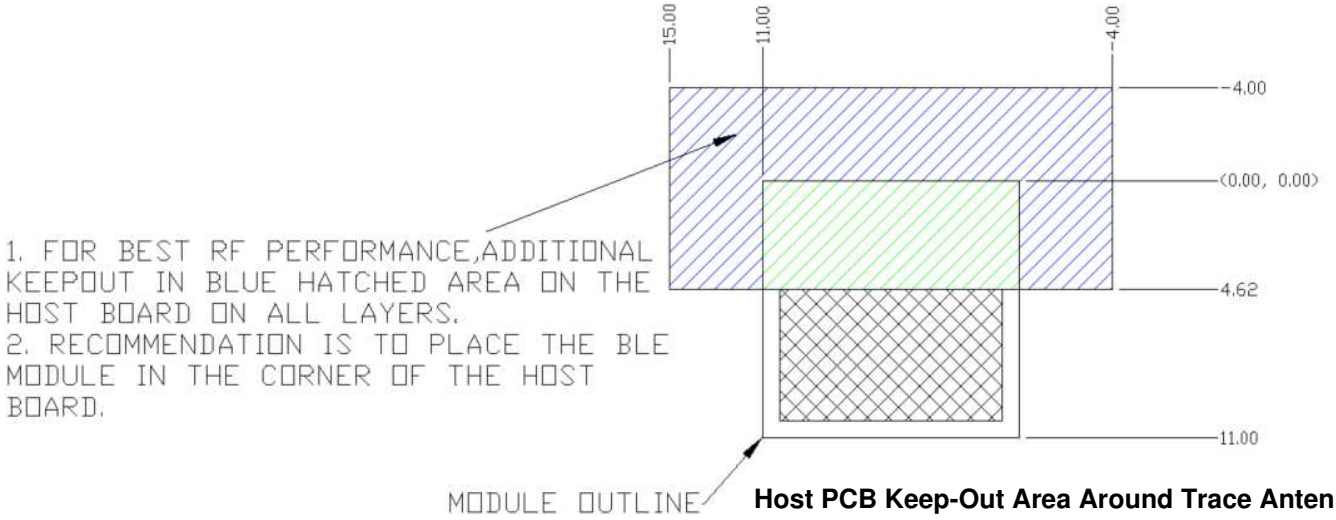
Figure 2. Solder Pad Dimensions (Seen from Bottom)



To maximize RF performance, the host layout should follow these recommendations:

1. The ideal placement of the Cypress BLE module is in a corner of the host board with the antenna located on the edge of the host board. This placement minimizes the additional recommended keep-out area stated in item 2. Refer to AN96841 for module placement best practices.
2. To maximize RF performance, the area immediately around the Cypress BLE module trace antenna should contain an additional keep-out area, where no grounding or signal traces are contained. The keep-out area applies to all layers of the host board. The recommended dimensions of the host PCB keep-out area are shown in Figure 3 (dimensions are in mm).

Figure 3. Recommended Host PCB Keep-Out Area Around the CYBLE-214009-00 Trace Antenna

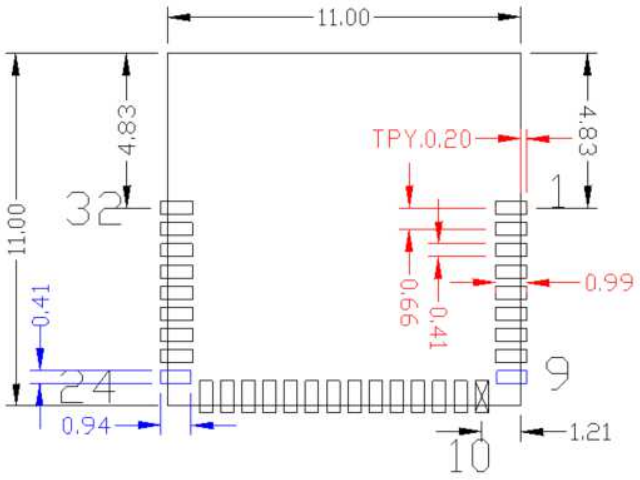


Host PCB Keep-Out Area Around Trace Antenna

Recommended Host PCB Layout

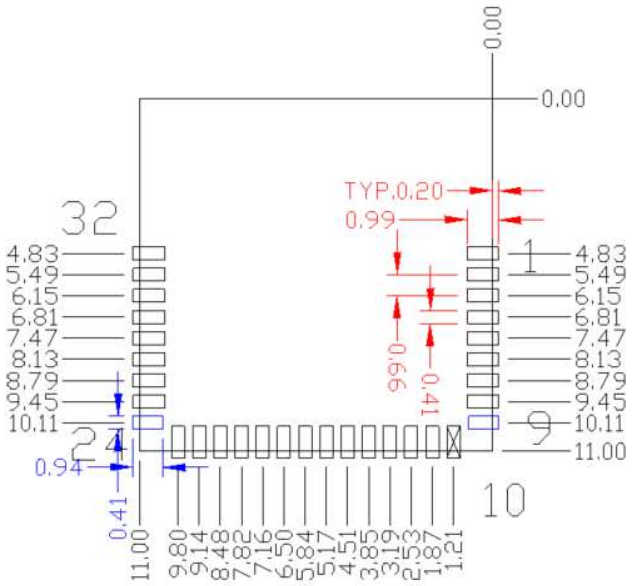
Figure 4 through Figure 6 and Table 3 provide details that can be used for the recommended host PCB layout pattern for the CYBLE-214009-00. Dimensions are in millimeters unless otherwise noted. Pad length of 0.99 mm (0.494 mm from center of the pad on either side) shown in Figure 6 is the minimum recommended host pad length. The host PCB layout pattern can be completed using either Figure 4, Figure 5, or Figure 6. It is not necessary to use all figures to complete the host PCB layout pattern.

Figure 4. Host Layout Pattern for CYBLE-214009-00



Top View (Seen on Host PCB)

Figure 5. Module Pad Location from Origin



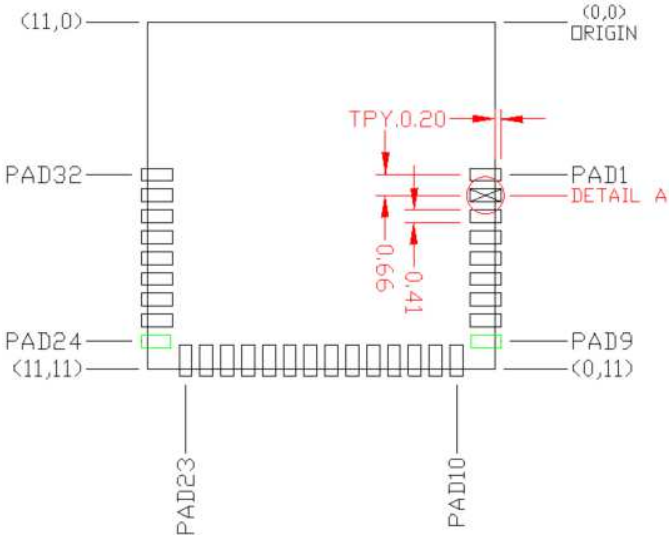
Top View (Seen on Host PCB)

Table 3 provides the center location for each solder pad on the CYBLE-214009-00. All dimensions are referenced to the center of the solder pad. Refer to Figure 6 for the location of each module solder pad.

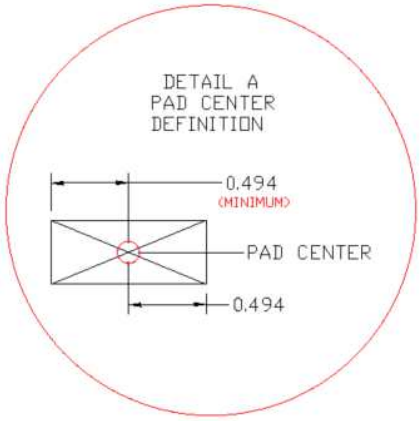
Table 3. Module Solder Pad Location

Solder Pad (Center of Pad)	Location (X,Y) from Origin (mm)	Dimension from Origin (mils)
1	(0.30, 4.83)	(11.81, 190.16)
2	(0.30, 5.49)	(11.81, 216.14)
3	(0.30, 6.15)	(11.81, 242.13)
4	(0.30, 6.81)	(11.81, 268.11)
5	(0.30, 7.47)	(11.81, 294.09)
6	(0.30, 8.13)	(11.81, 320.08)
7	(0.30, 8.79)	(11.81, 346.06)
8	(0.30, 9.45)	(11.81, 372.05)
9	(0.27, 10.11)	(10.63, 398.03)
10	(1.21, 10.70)	(47.64, 421.26)
11	(1.87, 10.70)	(73.62, 421.26)
12	(2.53, 10.70)	(99.61, 421.26)
13	(3.19, 10.70)	(125.59, 421.26)
14	(3.85, 10.70)	(151.57, 421.26)
15	(4.51, 10.70)	(177.56, 421.26)
16	(5.17, 10.70)	(203.54, 421.26)
17	(5.84, 10.70)	(229.92, 421.26)
18	(6.50, 10.70)	(255.91, 421.26)
19	(7.16, 10.70)	(281.89, 421.26)
20	(7.82, 10.70)	(307.87, 421.26)
21	(8.48, 10.70)	(333.86, 421.26)
22	(9.14, 10.70)	(359.84, 421.26)
23	(9.80, 10.70)	(385.83, 421.26)
24	(10.73, 10.11)	(422.44, 398.03)
25	(10.70, 9.45)	(421.26, 372.05)
26	(10.70, 8.79)	(421.26, 346.06)
27	(10.70, 8.13)	(421.26, 320.08)
28	(10.70, 7.47)	(421.26, 294.09)
29	(10.70, 6.81)	(421.26, 268.11)
30	(10.70, 6.15)	(421.26, 242.13)
31	(10.70, 5.49)	(421.26, 216.14)
32	(10.70, 4.83)	(421.26, 190.16)

Figure 6. Solder Pad Reference Location



Top View (Seen on Host PCB)



Digital and Analog Capabilities and Connections

Table 4 and Table 5 detail the solder pad connection definitions and available functions for each connection pad. Table 4 lists the solder pads on CYBLE-214009-00, the BLE device port-pin, and denotes whether the digital function shown is available for each solder pad. Table 5 denotes whether the analog function shown is available for each solder pad. Each connection is configurable for a single option shown with a ✓.

Table 4. Digital Peripheral Capabilities

Pad Number	Device Port Pin	UART	SPI	I²C	TCPWM[2,3]	Cap Sense	WCO Out	ECO OUT	LCD	SWD	GPIO
1	GND[4]	Ground Connection									
2	P1.1		✓(SCB1_SS1)		✓(TCPWM)	✓			✓		✓
3	P1.0				✓(TCPWM)	✓			✓		✓
4	P1.5	✓(SCB0_TX)	✓(SCB0_MISO)	✓(SCB0_SCL)	✓(TCPWM)	✓			✓		✓
5	P0.1	✓(SCB1_TX)	✓(SCB1_MISO)	✓(SCB1_SCL)	✓(TCPWM)	✓			✓		✓
6	P0.7	✓(SCB0_CTS)	✓(SCB0_SCLK)		✓(TCPWM)	✓			✓	✓ (SWDCLK)	✓
7	VDD	Digital Power Supply Input (1.71 to 5.5V)									
8	P1.4	✓(SCB0_RX)	✓(SCB0_MOSI)	✓(SCB0_SDA)	✓(TCPWM)	✓			✓		✓
9	P0.4	✓(SCB0_RX)	✓(SCB0_MOSI)	✓(SCB0_SDA)	✓(TCPWM)	✓		✓	✓		✓
10	P0.5	✓(SCB0_TX)	✓(SCB0_MISO)	✓(SCB0_SCL)	✓(TCPWM)	✓			✓		✓
11	P0.6	✓(SCB0_RTS)	✓(SCB0_SS0)		✓(TCPWM)	✓			✓	✓ (SWDIO)	✓
12	P1.2		✓(SCB1_SS2)		✓(TCPWM)	✓			✓		✓
13	V_{DDR}	Radio Power Supply (1.9V to 5.5V)									
14	P2.6				✓(TCPWM)	✓			✓		✓
15	P1.3		✓(SCB1_SS3)		✓(TCPWM)	✓			✓		✓
16	P3.0	✓(SCB0_RX)		✓(SCB0_SDA)	✓(TCPWM)	✓			✓		✓
17	P2.1		✓(SCB0_SS2)		✓(TCPWM)	✓			✓		✓
18	P2.2		✓(SCB0_SS3)		✓(TCPWM)	✓			✓		✓
19	P2.3				✓(TCPWM)	✓	✓		✓		✓
20	VDDA	Analog Power Supply Input (1.71 to 5.5V)									
21	P3.4	✓(SCB1_RX)		✓(SCB1_SDA)	✓(TCPWM)	✓			✓		✓
22	P3.1	✓(SCB0_TX)		✓(SCB0_SCL)	✓(TCPWM)	✓			✓		✓
23	P3.7	✓(SCB1_CTS)			✓(TCPWM)	✓	✓		✓		✓
24	P3.5	✓(SCB1_TX)		✓(SCB1_SCL)	✓(TCPWM)	✓			✓		✓
25	P3.3	✓(SCB0_CTS)			✓(TCPWM)	✓			✓		✓
26	VREF	Reference Voltage Input									
27	P3.2	✓(SCB0_RTS)			✓(TCPWM)	✓			✓		✓
28	P3.6	✓(SCB1_RTS)			✓(TCPWM)	✓			✓		✓
29	XRES	External Reset Hardware Connection Input									
30	P2.4				✓(TCPWM)	✓			✓		✓
31	P2.5				✓(TCPWM)	✓			✓		✓
32	GND	Ground Connection									

Notes
2. TCPWM stands for timer, counter, and PWM. If supported, the pad can be configured to any of these peripheral functions.
3. TCPWM connections on ports 0, 1, 2, and 3 can be routed through the Digital Signal Interconnect (DSI) to any of the TCPWM blocks and can be either positive or negative polarity.
4. The main board needs to connect both GND connections (Pad 1 and Pad 32) on the module to the common ground of the system.

Table 5. Analog Peripheral Capabilities

Pad Number	Device Port Pin	SARMUX	OPAMP	LPCOMP
1	GND[4]	Ground Connection		
2	P1.1		✓(CTBm1_OA0_INN)	
3	P1.0		✓(CTBm1_OA0_INP)	
4	P1.5		✓(CTBm1_OA1_INP)	
5	P0.1			
6	P0.7			
7	VDD	Digital Power Supply Input (1.71 to 5.5V)		
8	P1.4		✓(CTBm1_OA1_INN)	
9	P0.4			✓(COMP1_INP)
10	P0.5			✓(COMP1_INN)
11	P0.6			
12	P1.2		✓(CTBm1_OA0_OUT)	
13	V_{DDR}	Radio Power Supply (1.9V to 5.5V)		
14	P2.6		✓(CTBm0_OA0_INP)	
15	P1.3		✓(CTBm1_OA1_OUT)	
16	P3.0	✓		
17	P2.1		✓(CTBm0_OA0_INN)	
18	P2.2		✓(CTBm0_OA0_OUT)	
19	P2.3		✓(CTBm0_OA1_OUT)	
20	VDDA	Analog Power Supply Input (1.71 to 5.5V)		
21	P3.4	✓		
22	P3.1	✓		
23	P3.7	✓		
24	P3.5	✓		
25	P3.3	✓		
26	VREF	Reference Voltage Input (Optional)		
27	P3.2	✓		
28	P3.6	✓		
29	XRES	External Reset Hardware Connection Input		
30	P2.4		✓(CTBm0_OA1_INN)	
31	P2.5		✓(CTBm0_OA1_INP)	
32	GND	Ground Connection		

Power Supply Connections and Recommended External Components

Power Connections

The CYBLE-214009-00 contains three power supply connections, VDD, VDDA, and VDDR. The VDD and VDDA connections supply power for the digital and analog device operation respectively. VDDR supplies power for the device radio.

VDD and VDDA accept a supply range of 1.71 V to 5.5 V. VDDR accepts a supply range of 1.9 V to 5.5 V. These specifications can be found in Table 10. The maximum power supply ripple for both power connections on the module is 100 mV, as shown in Table 8.

The power supply ramp rate of VDD and VDDA must be equal to or greater than that of VDDR when the radio is used.

Connection Options

Two connection options are available for any application:

1. Single supply: Connect VDD, VDDA, and VDDR to the same supply.
2. Independent supply: Power VDD, VDDA, and VDDR separately.

External Component Recommendation

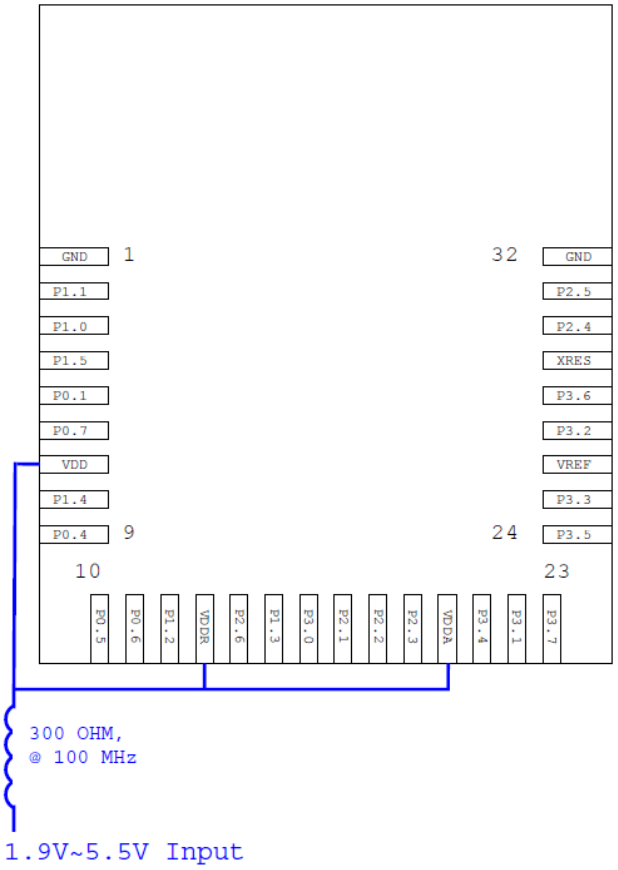
In either connection scenario, it is recommended to place an external ferrite bead between the supply and the module connection. The ferrite bead should be positioned as close as possible to the module pin connection.

Figure 7 details the recommended host schematic options for a single supply scenario. The use of one or three ferrite beads will depend on the specific application and configuration of the CYBLE-214009-00.

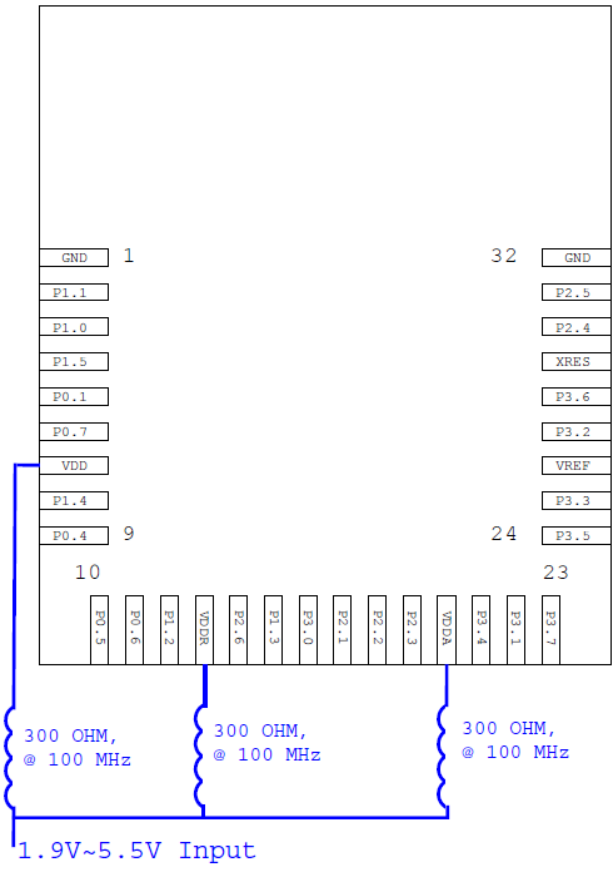
Figure 8 details the recommended host schematic for an independent supply scenario.

The recommended ferrite bead value is 330 Ω, 100 MHz (Murata BLM21PG331SN1D).

Figure 7. Recommended Host Schematic Options for Single Supply Option

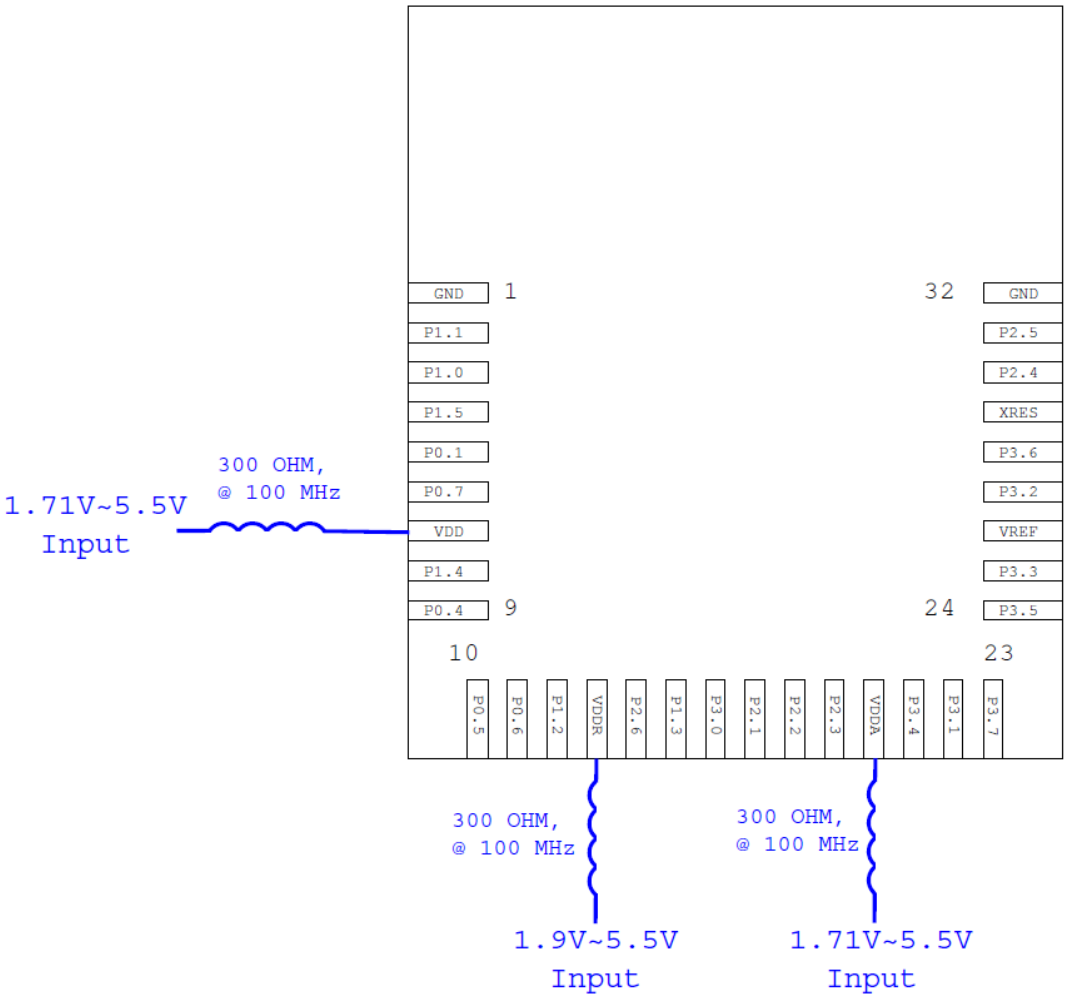


Single Ferrite Bead Option (Seen from Bottom)



Three Ferrite Bead Option (See from Bottom)

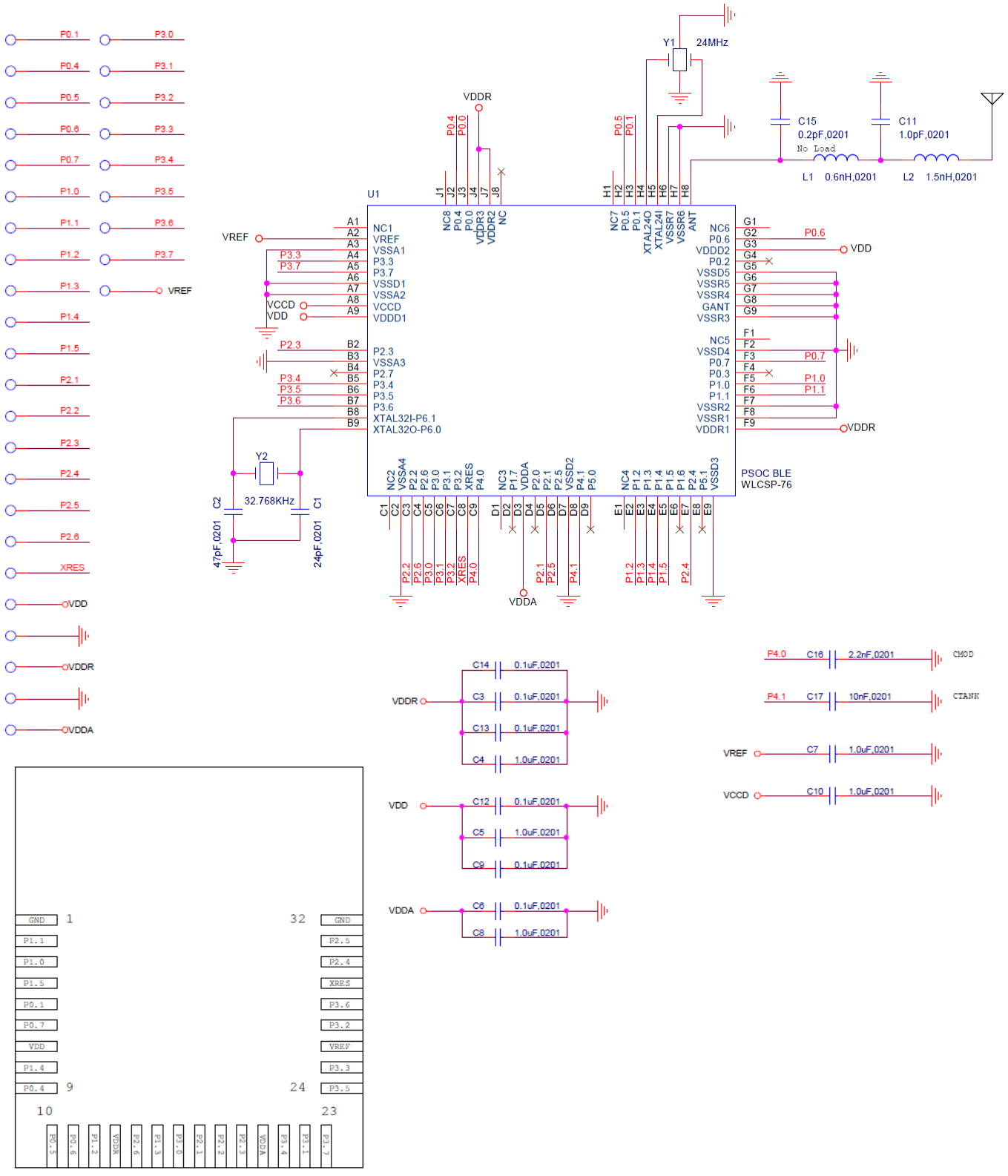
Figure 8. Recommended Host Schematic for Independent Supply Option



Independent Power Supply Option (Seen from Bottom)

The CYBLE-214009-00 schematic is shown in Figure 9.

Figure 9. CYBLE-214009-00 Schematic Diagram



Critical Components List

Table 6 details the critical components used in the CYBLE-214009-00 module.

Table 6. Critical Component List

Component	Reference Designator	Description
Silicon	U1	76-pin WLCSP Programmable System-on-Chip (PSoC) with BLE
Crystal	Y1	24.000 MHz, 10PF
Crystal	Y2	32.768 kHz, 12.5PF

Antenna Design

Table 7 details antenna used on the CYBLE-214009-00 module. The Cypress module performance improves many of these characteristics. For more information, see Table 9 on page 15.

Table 7. Trace Antenna Specifications

Item	Description
Frequency Range	2400–2500 MHz
Peak Gain	0.5-dBi typical
Average Gain	–0.5-dBi typical
Return Loss	10-dB minimum

Electrical Specification

Table 8 details the absolute maximum electrical characteristics for the Cypress BLE module.

Table 8. CYBLE-214009-00 Absolute Maximum Ratings

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
V_{DDD_ABS}	V_{DD}, V_{DDA}, or V_{DDR} supply relative to V_{SS} ($V_{SSD} = V_{SSA}$)	–0.5	–	6	V	Absolute maximum
V_{CCD_ABS}	Direct digital core voltage input relative to V_{SSD}	–0.5	–	1.95	V	Absolute maximum
V_{DDD_RIPPLE}	Maximum power supply ripple for V_{DD}, V_{DDA} and V_{DDR} input voltage	–	–	100	mV	3.0V supply Ripple frequency of 100 kHz to 750 kHz
V_{GPIO_ABS}	GPIO voltage	–0.5	–	V_{DD} +0.5	V	Absolute maximum
I_{GPIO_ABS}	Maximum current per GPIO	–25	–	25	mA	Absolute maximum
$I_{GPIO\_injection}$	GPIO injection current: Maximum for $V_{IH} > V_{DD}$ and minimum for $V_{IL} < V_{SS}$	–0.5	–	0.5	mA	Absolute maximum current injected per pin
LU	Pin current for latch up	–200		200	mA	–

Table 9 details the RF characteristics for the Cypress BLE module.

Table 9. CYBLE-214009-00 RF Performance Characteristics

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
RF_O	RF output power on ANT	–18	0	3	dBm	Configurable via register settings
RX_S	RF receive sensitivity on ANT	–	–87	–	dBm	Guaranteed by design simulation
F_R	Module frequency range	2400	–	2480	MHz	–
G_P	Peak gain	–	0.5	–	dBi	–
G_{Avg}	Average gain	–	–0.5	–	dBi	–
RL	Return loss	–	–10	–	dB	–

Table 10 through Table 51 list the module level electrical characteristics for the CYBLE-214009-00. All specifications are valid for –40 °C ≤ TA ≤ 85 °C and TJ ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 10. CYBLE-214009-00 DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
V_{DD1}	Power supply input voltage ($V_{DD} = V_{DDA} = V_{DDR}$)	1.71	–	5.5	V	With regulator enabled
V_{DD2}	Power supply input voltage unregulated ($V_{DD} = V_{DDA} = V_{DDR}$)	1.71	1.8	1.89	V	Internally unregulated supply
V_{DDR1}	Radio supply voltage (radio on)	1.9	–	5.5	V	–
V_{DDR2}	Radio supply voltage (radio off)	1.71	–	5.5	V	–
Active Mode, V_{DD} = 1.71 V to 5.5 V						
I_{DD3}	Execute from flash; CPU at 3 MHz	–	1.7	–	mA	T = 25 °C, V_{DD} = 3.3V
I_{DD4}	Execute from flash; CPU at 3 MHz	–	–	–	mA	T = –40 °C to 85 °C
I_{DD5}	Execute from flash; CPU at 6 MHz	–	2.5	–	mA	T = 25 °C, V_{DD} = 3.3V
I_{DD6}	Execute from flash; CPU at 6 MHz	–	–	–	mA	T = –40 °C to 85 °C
I_{DD7}	Execute from flash; CPU at 12 MHz	–	4	–	mA	T = 25 °C, V_{DD} = 3.3V

Table 10. CYBLE-214009-00 DC Specifications (continued)

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{DD8}	Execute from flash; CPU at 12 MHz	–	–	–	mA	T = –40 °C to 85 °C
I_{DD9}	Execute from flash; CPU at 24 MHz	–	7.1	–	mA	T = 25 °C, V_{DD} = 3.3V
I_{DD10}	Execute from flash; CPU at 24 MHz	–	–	–	mA	T = –40 °C to 85 °C
I_{DD11}	Execute from flash; CPU at 48 MHz	–	13.4	–	mA	T = 25 °C, V_{DD} = 3.3V
I_{DD12}	Execute from flash; CPU at 48 MHz	–	–	–	mA	T = –40 °C to 85 °C
Sleep Mode, V_{DD} = 1.71 V to 5.5 V						
I_{DD13}	IMO on	–	–	–	mA	T = 25 °C, V_{DD} = 3.3V, SYSCLK = 3 MHz
Sleep Mode, V_{DD} and V_{DDR} = 1.9 V to 5.5 V						
I_{DD14}	ECO on	–	–	–	mA	T = 25 °C, V_{DD} = 3.3V, SYSCLK = 3 MHz
Deep-Sleep Mode, V_{DD} = 1.71 V to 3.6 V						
I_{DD15}	WDT with WCO on	–	1.3	–	µA	T = 25 °C, V_{DD} = 3.3V
I_{DD16}	WDT with WCO on	–	–	–	µA	T = –40 °C to 85 °C
I_{DD17}	WDT with WCO on	–	–	–	µA	T = 25 °C, V_{DD} = 5V
I_{DD18}	WDT with WCO on	–	–	–	µA	T = –40 °C to 85 °C
Deep-Sleep Mode, V_{DD} = 1.71 V to 1.89 V (Regulator Bypassed)						
I_{DD19}	WDT with WCO on	–	–	–	µA	T = 25 °C
I_{DD20}	WDT with WCO on	–	–	–	µA	T = –40 °C to 85 °C
Hibernate Mode, V_{DD} = 1.71 V to 3.6 V						
I_{DD27}	GPIO and reset active	–	150	–	nA	T = 25 °C, V_{DD} = 3.3V
I_{DD28}	GPIO and reset active	–	–	–	nA	T = –40 °C to 85 °C
Hibernate Mode, V_{DD} = 3.6 V to 5.5 V						
I_{DD29}	GPIO and reset active	–	–	–	nA	T = 25 °C, V_{DD} = 5V
I_{DD30}	GPIO and reset active	–	–	–	nA	T = –40 °C to 85 °C
Stop Mode, V_{DD} = 1.71 V to 3.6 V						
I_{DD33}	Stop-mode current (V_{DD})	–	20	–	nA	T = 25 °C, V_{DD} = 3.3V
I_{DD34}	Stop-mode current (V_{DDR})	–	40	–-	nA	T = 25 °C, V_{DDR} = 3.3V
I_{DD35}	Stop-mode current (V_{DD})	–	–	–	nA	T = –40 °C to 85 °C
I_{DD36}	Stop-mode current (V_{DDR})	–	–	–	nA	T = –40 °C to 85 °C, V_{DDR} = 1.9 V to 3.6V
Stop Mode, V_{DD} = 3.6 V to 5.5 V						
I_{DD37}	Stop-mode current (V_{DD})	–	–	–	nA	T = 25 °C, V_{DD} = 5V
I_{DD38}	Stop-mode current (V_{DDR})	–	–	–	nA	T = 25 °C, V_{DDR} = 5V
I_{DD39}	Stop-mode current (V_{DD})	–	–	–	nA	T = –40 °C to 85 °C
I_{DD40}	Stop-mode current (V_{DDR})	–	–	–	nA	T = –40 °C to 85 °C

Table 11. AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
F_{CPU}	CPU frequency	DC	–	48	MHz	$1.71V \le V_{DD} \le 5.5V$
T_{SLEEP}	Wakeup from Sleep mode	–	0	–	µs	Guaranteed by characterization
$T_{DEEPSLEEP}$	Wakeup from Deep-Sleep mode	–	–	25	µs	24-MHz IMO. Guaranteed by characterization
$T_{HIBERNATE}$	Wakeup from Hibernate mode	–	–	800	µs	Guaranteed by characterization
T_{STOP}	Wakeup from Stop mode	–	–	2	ms	XRES wakeup

GPIO

Table 12. GPIO DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
V_{IH}[5]	Input voltage HIGH threshold	$0.7 \times V_{DD}$	–	–	V	CMOS input
	LVTTL input, $V_{DD} < 2.7V$	$0.7 \times V_{DD}$	–	–	V	–
	LVTTL input, $V_{DD} \ge 2.7V$	2.0	–	–	V	–
V_{IL}	Input voltage LOW threshold	–	–	$0.3 \times V_{DD}$	V	CMOS input
	LVTTL input, $V_{DD} < 2.7V$	–	–	$0.3 \times V_{DD}$	V	–
	LVTTL input, $V_{DD} \ge 2.7V$	–	–	0.8	V	–
V_{OH}	Output voltage HIGH level	$V_{DD} - 0.6$	–	–	V	I_{OH} = 4 mA at 3.3-V V_{DD}
	Output voltage HIGH level	$V_{DD} - 0.5$	–	–	V	I_{OH} = 1 mA at 1.8-V V_{DD}
V_{OL}	Output voltage LOW level	–	–	0.6	V	I_{OL} = 8 mA at 3.3-V V_{DD}
	Output voltage LOW level	–	–	0.6	V	I_{OL} = 4 mA at 1.8-V V_{DD}
	Output voltage LOW level	–	–	0.4	V	I_{OL} = 3 mA at 3.3-V V_{DD}
R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	–
$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	kΩ	–
I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, V_{DD} = 3.3V
I_{IL_CTBM}	Input leakage on CTBm input pins	–	–	4	nA	–
C_{IN}	Input capacitance	–	–	7	pF	–
V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DD} > 2.7V$
$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 \times V_{DD}$	–	–	1	–
I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	µA	–
I_{TOT_GPIO}	Maximum total source or sink chip current	–	–	200	mA	–

Note
5. V_{IH} must not exceed V_{DD} + 0.2 V.

Table 13. GPIO AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
T_{RISEF}	Rise time in Fast-Strong mode	2	–	12	ns	3.3-V V_{DDD}, C_{LOAD} = 25 pF
T_{FALLF}	Fall time in Fast-Strong mode	2	–	12	ns	3.3-V V_{DDD}, C_{LOAD} = 25 pF
T_{RISES}	Rise time in Slow-Strong mode	10	–	60	ns	3.3-V V_{DDD}, C_{LOAD} = 25 pF
T_{FALLS}	Fall time in Slow-Strong mode	10	–	60	ns	3.3-V V_{DDD}, C_{LOAD} = 25 pF
$F_{GPIOUT1}$	GPIO Fout; 3.3V ≤ V_{DD} ≤ 5.5V Fast-Strong mode	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
$F_{GPIOUT2}$	GPIO Fout; 1.7V≤ V_{DD} ≤ 3.3V Fast-Strong mode	–	–	16.7	MHz	90/10%, 25 pF load, 60/40 duty cycle
$F_{GPIOUT3}$	GPIO Fout; 3.3V ≤ V_{DD} ≤ 5.5V Slow-Strong mode	–	–	7	MHz	90/10%, 25 pF load, 60/40 duty cycle
$F_{GPIOUT4}$	GPIO Fout; 1.7V ≤ V_{DD} ≤ 3.3V Slow-Strong mode	–	–	3.5	MHz	90/10%, 25 pF load, 60/40 duty cycle
F_{GPIOIN}	GPIO input operating frequency 1.71V ≤ V_{DD} ≤ 5.5V	–	–	48	MHz	90/10% V_{IO}

XRES

Table 14. XRES DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
V_{IH}	Input voltage HIGH threshold	0.7 × V_{DDD}	–	–	V	CMOS input
V_{IL}	Input voltage LOW threshold	–	–	0.3 × V_{DDD}	V	CMOS input
R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	–
C_{IN}	Input capacitance	–	3	–	pF	–
$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	–
I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	µA	–

Table 15. XRES AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$T_{RESETWIDTH}$	Reset pulse width	1	–	–	µs	–

Analog Peripherals

Opamp

Table 16. Opamp Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{DD} (Opamp Block Current. V_{DD} = 1.8 V. No Load)						
I_{DD_HI}	Power = high	–	1000	1300	µA	–
I_{DD_MED}	Power = medium	–	500	–	µA	–
I_{DD_LOW}	Power = low	–	250	350	µA	–
GBW (Load = 20 pF, 0.1 mA. V_{DDA} = 2.7 V)						
GBW_HI	Power = high	6	–	–	MHz	–
GBW_MED	Power = medium	4	–	–	MHz	–
GBW_LO	Power = low	–	1	–	MHz	–
I_{OUT_MAX} (V_{DDA} ≥ 2.7 V, 500 mV from Rail)						
$I_{OUT\_MAX\_HI}$	Power = high	10	–	–	mA	–

Table 16. Opamp Specifications (continued)

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$I_{OUT\_MAX\_MID}$	Power = medium	10	–	–	mA	–
$I_{OUT\_MAX\_LO}$	Power = low	–	5	–	mA	–
I_{OUT} (V_{DDA} = 1.71 V, 500 mV from Rail)						
$I_{OUT\_MAX\_HI}$	Power = high	4	–	–	mA	–
$I_{OUT\_MAX\_MID}$	Power = medium	4	–	–	mA	–
$I_{OUT\_MAX\_LO}$	Power = low	–	2	–	mA	–
V_{IN}	Charge pump on, $V_{DDA} \geq 2.7$ V	–0.05	–	$V_{DDA} – 0.2$	V	–
V_{CM}	Charge pump on, $V_{DDA} \geq 2.7$ V	–0.05	–	$V_{DDA} – 0.2$	V	–
V_{OUT} ($V_{DDA} \geq 2.7$ V)						
V_{OUT_1}	Power = high, I_{LOAD} = 10 mA	0.5	–	$V_{DDA} – 0.5$	V	–
V_{OUT_2}	Power = high, I_{LOAD} = 1 mA	0.2	–	$V_{DDA} – 0.2$	V	–
V_{OUT_3}	Power = medium, I_{LOAD} = 1 mA	0.2	–	$V_{DDA} – 0.2$	V	–
V_{OUT_4}	Power = low, I_{LOAD} = 0.1 mA	0.2	–	$V_{DDA} – 0.2$	V	–
V_{OS_TR}	Offset voltage, trimmed	1	±0.5	1	mV	High mode
V_{OS_TR}	Offset voltage, trimmed	–	±1	–	mV	Medium mode
V_{OS_TR}	Offset voltage, trimmed	–	±2	–	mV	Low mode
$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–10	±3	10	µV/°C	High mode
$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–	±10	–	µV/°C	Medium mode
$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–	±10	–	µV/°C	Low mode
CMRR	DC	65	70	–	dB	V_{DDD} = 3.6 V, High-power mode
PSRR	At 1 kHz, 100-mV ripple	70	85	–	dB	V_{DDD} = 3.6 V
Noise						
V_{N1}	Input referred, 1 Hz–1 GHz, power = high	–	94	–	µVrms	–
V_{N2}	Input referred, 1 kHz, power = high	–	72	–	nV/rtHz	–
V_{N3}	Input referred, 10 kHz, power = high	–	28	–	nV/rtHz	–
V_{N4}	Input referred, 100 kHz, power = high	–	15	–	nV/rtHz	–
C_{LOAD}	Stable up to maximum load. Performance specs at 50 pF	–	–	125	pF	–
Slew_rate	Cload = 50 pF, Power = High, $V_{DDA} \geq 2.7$ V	6	–	–	V/µs	–
T_op_wake	From disable to enable, no external RC dominating	–	300	–	µs	–
Comp_mode (Comparator Mode; 50-mV Drive, T_{RISE} = T_{FALL} (Approx.)						
T_{PD1}	Response time; power = high	–	150	–	ns	–
T_{PD2}	Response time; power = medium	–	400	–	ns	–
T_{PD3}	Response time; power = low	–	2000	–	ns	–
Vhyst_op	Hysteresis	–	10	–	mV	–
Deep-Sleep Mode (Deep-Sleep mode operation is only guaranteed for V_{DDA} > 2.5 V)						
GBW_DS	Gain bandwidth product	–	50	–	kHz	–
IDD_DS	Current	–	15	–	µA	–
Vos_DS	Offset voltage	–	5	–	mV	–
Vos_dr_DS	Offset voltage drift	–	20	–	µV/°C	–
Vout_DS	Output voltage	0.2	–	V_{DD}–0.2	V	–
Vcm_DS	Common mode voltage	0.2	–	$V_{DD} – 1.8$	V	–

Table 17. Comparator DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$V_{OFFSET1}$	Input offset voltage, Factory trim	–	–	±10	mV	–
$V_{OFFSET2}$	Input offset voltage, Custom trim	–	–	±6	mV	–
$V_{OFFSET3}$	Input offset voltage, ultra-low-power mode	–	±12	–	mV	–
V_{HYST}	Hysteresis when enabled	–	10	35	mV	–
V_{ICM1}	Input common mode voltage in normal mode	0	–	V_{DDD} – 0.1	V	Modes 1 and 2
V_{ICM2}	Input common mode voltage in low-power mode	0	–	V_{DDD}	V	–
V_{ICM3}	Input common mode voltage in ultra low-power mode	0	–	V_{DDD} – 1.15	V	–
CMRR	Common mode rejection ratio	50	–	–	dB	$V_{DDD} \geq 2.7$ V
CMRR	Common mode rejection ratio	42	–	–	dB	$V_{DDD} \leq 2.7$ V
I_{CMP1}	Block current, normal mode	–	–	400	µA	–
I_{CMP2}	Block current, low-power mode	–	–	100	µA	–
I_{CMP3}	Block current in ultra-low-power mode	–	6	–	µA	–
Z_{CMP}	DC input impedance of comparator	35	–	–	MΩ	–

Table 18. Comparator AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
T_{RESP1}	Response time, normal mode, 50-mV overdrive	–	38	–	ns	50-mV overdrive
T_{RESP2}	Response time, low-power mode, 50-mV overdrive	–	70	–	ns	50-mV overdrive
T_{RESP3}	Response time, ultra-low-power mode, 50-mV overdrive	–	2.3	–	µs	200-mV overdrive

Temperature Sensor

Table 19. Temperature Sensor Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$T_{SENSACC}$	Temperature-sensor accuracy	–5	±1	5	°C	–40 to +85 °C

SAR ADC

Table 20. SAR ADC DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
A_RES	Resolution	–	–	12	bits	–
A_CHNIS_S	Number of channels - single-ended	–	–	8	–	8 full-speed
A-CHNKS_D	Number of channels - differential	–	–	4	–	Diff inputs use neighboring I/O
A-MONO	Monotonicity	–	–	–	–	Yes
A_GAINERR	Gain error	–	–	±0.1	%	With external reference
A_OFFSET	Input offset voltage	–	–	2	mV	Measured with 1-V V_{REF}
A_ISAR	Current consumption	–	–	1	mA	–
A_VINS	Input voltage range - single-ended	V_{SS}	–	V_{DDA}	V	–

Table 20. SAR ADC DC Specifications (continued)

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
A_VIND	Input voltage range - differential	V_{SS}	–	V_{DDA}	V	–
A_INRES	Input resistance	–	–	2.2	kΩ	–
A_INCAP	Input capacitance	–	–	10	pF	–
VREFSAR	Trimmed internal reference to SAR	–1	–	1	%	Percentage of Vbg (1.024 V)

Table 21. SAR ADC AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
A_PSRR	Power-supply rejection ratio	70	–	–	dB	Measured at 1-V reference
A_CMRR	Common-mode rejection ratio	66	–	–	dB	–
A_SAMP	Sample rate	–	–	1	Msps	–
Fsarintref	SAR operating speed without external ref. bypass	–	–	100	ksps	12-bit resolution
A_SNR	Signal-to-noise ratio (SNR)	65	–	–	dB	F_{IN} = 10 kHz
A_BW	Input bandwidth without aliasing	–	–	A_SAMP/2	kHz	–
A_INL	Integral nonlinearity. V_{DD} = 1.71 V to 5.5 V, 1 Msps	–1.7	–	2	LSB	V_{REF} = 1 V to V_{DD}
A_INL	Integral nonlinearity. V_{DDD} = 1.71 V to 3.6 V, 1 Msps	–1.5	–	1.7	LSB	V_{REF} = 1.71 V to V_{DD}
A_INL	Integral nonlinearity. V_{DD} = 1.71 V to 5.5 V, 500 ksps	–1.5	–	1.7	LSB	V_{REF} = 1 V to V_{DD}
A_dnl	Differential nonlinearity. V_{DD} = 1.71 V to 5.5 V, 1 Msps	–1	–	2.2	LSB	V_{REF} = 1 V to V_{DD}
A_DNL	Differential nonlinearity. V_{DD} = 1.71 V to 3.6 V, 1 Msps	–1	–	2	LSB	V_{REF} = 1.71 V to V_{DD}
A_DNL	Differential nonlinearity. V_{DD} = 1.71 V to 5.5 V, 500 ksps	–1	–	2.2	LSB	V_{REF} = 1 V to V_{DD}
A_THD	Total harmonic distortion	–	–	–65	dB	F_{IN} = 10 kHz

CSD

Table 22. CSD Block Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
V_{CSD}	Voltage range of operation	1.71	–	5.5	V	–
IDAC1	DNL for 8-bit resolution	–1	–	1	LSB	–
IDAC1	INL for 8-bit resolution	–3	–	3	LSB	–
IDAC2	DNL for 7-bit resolution	–1	–	1	LSB	–
IDAC2	INL for 7-bit resolution	–3	–	3	LSB	–
SNR	Ratio of counts of finger to noise	5	–	–	Ratio	Capacitance range of 9 pF to 35 pF, 0.1-pF sensitivity. Radio is not operating during the scan
I_{DAC1_CRT1}	Output current of IDAC1 (8 bits) in High range	–	612	–	µA	–
I_{DAC1_CRT2}	Output current of IDAC1 (8 bits) in Low range	–	306	–	µA	–

Table 22. CSD Block Specifications (continued)

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{DAC2_CRT1}	Output current of IDAC2 (7 bits) in High range	–	305	–	µA	–
I_{DAC2_CRT2}	Output current of IDAC2 (7 bits) in Low range	–	153	–	µA	–

Digital Peripherals

Timer

Table 23. Timer DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{TIM1}	Block current consumption at 3 MHz	–	–	42	µA	16-bit timer
I_{TIM2}	Block current consumption at 12 MHz	–	–	130	µA	16-bit timer
I_{TIM3}	Block current consumption at 48 MHz	–	–	535	µA	16-bit timer

Table 24. Timer AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$T_{TIMFREQ}$	Operating frequency	F_{CLK}	–	48	MHz	–
$T_{CAPWINT}$	Capture pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{CAPWEXT}$	Capture pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
T_{TIMRES}	Timer resolution	T_{CLK}	–	–	ns	–
$T_{TENWIDINT}$	Enable pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{TENWIDEXT}$	Enable pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
$T_{TIMRESWINT}$	Reset pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{TIMRESEXT}$	Reset pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–

Counter

Table 25. Counter DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{CTR1}	Block current consumption at 3 MHz	–	–	42	µA	16-bit counter
I_{CTR2}	Block current consumption at 12 MHz	–	–	130	µA	16-bit counter
I_{CTR3}	Block current consumption at 48 MHz	–	–	535	µA	16-bit counter

Table 26. Counter AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$T_{CTRFREQ}$	Operating frequency	F_{CLK}	–	48	MHz	–
$T_{CTRPWINT}$	Capture pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{CTRPWEXT}$	Capture pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
T_{CTRES}	Counter Resolution	T_{CLK}	–	–	ns	–
$T_{CENWIDINT}$	Enable pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{CENWIDEXT}$	Enable pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
$T_{CTRRESWINT}$	Reset pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{CTRRESWEXT}$	Reset pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–

Pulse Width Modulation (PWM)

Table 27. PWM DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{PWM1}	Block current consumption at 3 MHz	–	–	42	µA	16-bit PWM
I_{PWM2}	Block current consumption at 12 MHz	–	–	130	µA	16-bit PWM
I_{PWM3}	Block current consumption at 48 MHz	–	–	535	µA	16-bit PWM

Table 28. PWM AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$T_{PWMFREQ}$	Operating frequency	F_{CLK}	–	48	MHz	–
$T_{PWMPWINT}$	Pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
T_{PWMEXT}	Pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
$T_{PWMKILLINT}$	Kill pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{PWMKILLEXT}$	Kill pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
$T_{PWMEINT}$	Enable pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{PWMENEXT}$	Enable pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–
$T_{PWMRESWINT}$	Reset pulse width (internal)	$2 \times T_{CLK}$	–	–	ns	–
$T_{PWMRESWEXT}$	Reset pulse width (external)	$2 \times T_{CLK}$	–	–	ns	–

LCD Direct Drive

Table 29. LCD Direct Drive DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
SID228	I_{LCDLOW}	Operating current in low-power mode	–	17.5	–	µA	16 × 4 small segment display at 50 Hz
SID229	C_{LCDCAP}	LCD capacitance per segment/common driver	–	500	5000	pF	–
SID230	LCD_{OFFSET}	Long-term segment offset	–	20	–	mV	–
SID231	I_{LCDOP1}	LCD system operating current V_{BIAS} = 5 V	–	2	–	mA	32 × 4 segments. 50 Hz at 25 °C
SID232	I_{LCDOP2}	LCD system operating current V_{BIAS} = 3.3 V	–	2	–	mA	32 × 4 segments 50 Hz at 25 °C

Table 30. LCD Direct Drive AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
SID233	F_{LCD}	LCD frame rate	10	50	150	Hz	–

Serial Communication

Table 31. Fixed I²C DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{I2C1}	Block current consumption at 100 kHz	–	–	50	µA	–
I_{I2C2}	Block current consumption at 400 kHz	–	–	155	µA	–
I_{I2C3}	Block current consumption at 1 Mbps	–	–	390	µA	–
I_{I2C4}	I²C enabled in Deep-Sleep mode	–	–	1.4	µA	–

Table 32. Fixed I²C AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
F_{I2C1}	Bit rate	–	–	400	kHz	–

Table 33. Fixed UART DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{UART1}	Block current consumption at 100 kbps	–	–	55	µA	–
I_{UART2}	Block current consumption at 1000 kbps	–	–	312	µA	–

Table 34. Fixed UART AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
F_{UART}	Bit rate	–	–	1	Mbps	–

Table 35. Fixed SPI DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
I_{SPI1}	Block current consumption at 1 Mbps	–	–	360	µA	–
I_{SPI2}	Block current consumption at 4 Mbps	–	–	560	µA	–
I_{SPI3}	Block current consumption at 8 Mbps	–	–	600	µA	–

Table 36. Fixed SPI AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
F_{SPI}	SPI operating frequency (master; 6x over sampling)	–	–	8	MHz	–

Table 37. Fixed SPI Master Mode AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
T_{DMO}	MOSI valid after SCLK driving edge	–	–	18	ns	–
T_{DSI}	MISO valid before SCLK capturing edge Full clock, late MISO sampling used	20	–	–	ns	Full clock, late MISO sampling
T_{HMO}	Previous MOSI data hold time	0	–	–	ns	Referred to Slave capturing edge

Table 38. Fixed SPI Slave Mode AC Specifications

Parameter	Description	Min	Typ	Max	Unit	
T_{DMI}	MOSI valid before SCLK capturing edge	40	–	–	ns	
T_{DSO}	MISO valid after SCLK driving edge	–	–	$42 + 3 \times T_{CPU}$	ns	
T_{DSO_ext}	MISO Valid after SCLK driving edge in external clock mode. $V_{DD} < 3.0$ V	–	–	50	ns	
T_{HSO}	Previous MISO data hold time	0	–	–	ns	
$T_{SSELSCK}$	SSEL valid to first SCK valid edge	100	–	–	ns	

Memory

Table 39. Flash DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
V_{PE}	Erase and program voltage	1.71	–	5.5	V	–
T_{WS48}	Number of Wait states at 32–48 MHz	2	–	–	_	CPU execution from flash
T_{WS32}	Number of Wait states at 16–32 MHz	1	–	–	_	CPU execution from flash
T_{WS16}	Number of Wait states for 0–16 MHz	0	–	–	_	CPU execution from flash

Table 40. Flash AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$T_{ROWWRITE}$[6]	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 256 bytes
$T_{ROWERASE}$[6]	Row erase time	–	–	13	ms	–
$T_{ROWPROGRAM}$[6]	Row program time after erase	–	–	7	ms	–
$T_{BULKERASE}$[6]	Bulk erase time (256 KB)	–	–	35	ms	–
$T_{DEVPROG}$[6]	Total device program time	–	–	25	seconds	–
F_{END}	Flash endurance	100 K	–	–	cycles	–
F_{RET}	Flash retention. $T_A \le 55$ °C, 100 K P/E cycles.	20	–	–	years	–
F_{RET2}	Flash retention. $T_A \le 85$ °C, 10 K P/E cycles.	10	–	–	years	–

System Resources

Power-on-Reset (POR)

Table 41. POR DC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$V_{RISEIPOR}$	Rising trip voltage	0.80	–	1.45	V	–
$V_{FALLIPOR}$	Falling trip voltage	0.75	–	1.40	V	–
$V_{IPORHYST}$	Hysteresis	15	–	200	mV	–

Table 42. POR AC Specifications

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
T_{PPOR_TR}	Precision power-on reset (PPOR) response time in Active and Sleep modes	–	–	1	µs	–

Table 43. Brown-Out Detect

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$V_{FALLPPOR}$	BOD trip voltage in Active and Sleep modes	1.64	–	–	V	–
$V_{FALLDPSLP}$	BOD trip voltage in Deep Sleep	1.4	–	–	V	–

Table 44. Hibernate Reset

Parameter	Description	Min	Typ	Max	Unit	Details/Conditions
$V_{HBRTRIP}$	BOD trip voltage in Hibernate	1.1	–	–	V	–

Note

6. It can take as much as 20 ms to write to flash. During this time, the device should not be reset, or flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.